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APS-01-002B

May 21, 2004

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: Serial No. 10/826,752 04/16/04

Romeo Emmanuel J. Alvarez

METHOD FOR FORMING A WAFER LEVEL CHIP SCALE PACKAGE, AND PACKAGE FORMED THEREBY

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 24, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 5/24/04

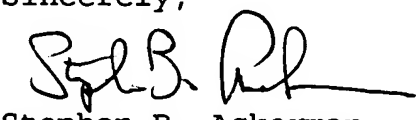
U.S. Patent 6,072,236 to Akram et al., "Micromachined Chip Scale Package," discloses a wafer level process utilizing micromachining to fabricated chip scale packages.

U.S. Patent 6,468,892 to Baker et al., "Front Side Coating for Bump Devices," describes a method utilizing a solder mask at the wafer level for forming bumps on chip scale packages.

U.S. Patent Application Publication US 2002/0027257 A1 to Kinsman et al., "Method for Fabricating a Chip Scale Package Using Wafer Level Processing and Devices Resulting Therefrom," describes a method for fabricating a chip scale package utilizing wafer level processing.

U.S. Patent 6,578,754 to Tung, "Pillar Connections for Semiconductor Chips and Method of Manufacture," discusses pillar-shaped connections from a semiconductor chip to a substrate and method for making the connections.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)	Application Number
APS-01-002B	10/826,752
Applicant: Romeo Emmanuel Alvarez	
Filing Date: 04/16/04	Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6072236	6/6/00	Akram et al.	257	698	3/7/96
	6468892	10/22/02	Baker et al.	438	612	7/14/00
	6578754	6/17/03	Tung	228	180.22	4/27/00

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PATENT & TRADEMARK OFFICE
SC 1105

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES	Translation NO

OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

* -	US Patent App. Pub. US 2002/0027257 A1 to Kinsman et al., Pub. Date 3/7/02, Filed 7/27/01, US Cl. 257/400.

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

* Not found